

March 1995 Revised March 2001

74LCX541

Low Voltage Octal Buffer/Line Driver with 5V Tolerant Inputs and Outputs

General Description

The LCX541 is an octal buffer/line driver designed to be employed as memory and address drivers, clock drivers and bus oriented transmitter/receivers. The LCX541 is a non inverting option of the LCX540.

This device is similar in function to the LCX244 while providing flow-through architecture (inputs on opposite side from outputs). This pinout arrangement makes this device especially useful as an output port for microprocessors, allowing ease of layout and greater PC board density.

The LCX541 is designed for low voltage (2.5V or 3.3V) V_{CC} applications with capability of interfacing to a 5V signal environment. The LCX541 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant input and outputs
- 2.3V-3.6V V_{CC} specifications provided
- 6.5 ns t_{PD} max ($V_{CC} = 3.3V$), 10 μ A I_{CC} max
- Power-down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- \pm 24 mA output drive ($V_{CC} = 3.0V$)
- Implements patented noise/ EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:

Human body model > 2000V

Machine model > 200V

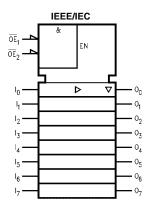
Note 1: To ensure the high-impedance state during power up or down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

Ordering Code:

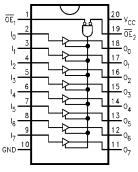
Order Number	Package Number	Package Description
74LCX541WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LCX541SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LCX541MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74LCX541MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol



Connection Diagram



Pin Descriptions

Pin Names	Description	
$\overline{OE}_1, \overline{OE}_2$	3-STATE Output Enable Inputs	
l ₀ , l ₇	Inputs	
O ₀ , O ₇	Outputs	

Truth Table

	Outputs		
OE ₁	OE ₂	I	O _n
L	L	Н	Н
Н	Χ	Χ	Z
Х	Н	Χ	Z
L	L	L	L

H = HIGH Voltage Level L = LOW Voltage Level X = Immaterial Z = High Impedance

Absolute Maximum Ratings(Note 2) Symbol Parameter Value Conditions Units -0.5 to +7.0 ٧ Supply Voltage V_{CC} ٧ DC Input Voltage -0.5 to +7.0 V_{I} DC Output Voltage Output in 3-STATE Vo -0.5 to +7.0 ٧ Output in HIGH or LOW State (Note 3) -0.5 to $V_{CC} + 0.5$ DC Input Diode Current -50 V_I < GND mΑ I_{IK} DC Output Diode Current -50 V_O < GND mΑ +50 $V_O > V_{CC}$ DC Output Source/Sink Current ±50 mΑ lο I_{CC} DC Supply Current per Supply Pin ±100 mΑ DC Ground Current per Ground Pin ±100 mΑ I_{GND} Storage Temperature -65 to +150 °C T_{STG}

Recommended Operating Conditions (Note 4)

Symbol	Parameter	Min	Max	Units	
V _{CC}	Supply Voltage	Operating	2.0	3.6	V
		Data Retention	1.5	3.6	V
V _I	Input Voltage		0	5.5	V
V _O	Output Voltage	HIGH or LOW State	0	V _{CC}	V
		3-STATE	0	5.5	V
I _{OH} /I _{OL}	Output Current	$V_{CC} = 3.0V - 3.6V$		±24	
		$V_{CC} = 2.7V - 3.0V$ $V_{CC} = 2.3V - 2.7V$		±12	mA
		$V_{CC} = 2.3V - 2.7V$		±8	
T _A	Free-Air Operating Temperature		-40	85	°C
Δt/ΔV	Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V		0	10	ns/V

Note 2: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 3: I_O Absolute Maximum Rating must be observed.

Note 4: Unused inputs or I/O's must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	Conditions	v _{cc}	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		Units	
Syllibol		Conditions	(V)	Min	Max	Units	
/ _{IH}	HIGH Level Input Voltage		2.3 – 2.7	1.7		V	
			2.7 – 3.6	2.0			
/ _{IL}	LOW Level Input Voltage		2.3 – 2.7		0.7	V	
			2.7 – 3.6		0.8		
/он	HIGH Level Output Voltage	$I_{OH} = -100\mu A$	2.3 – 3.6	V _{CC} - 0.2			
		I _{OH} = -8 mA	2.3	1.8			
		I _{OH} = -12 mA	2.7	2.2		V	
		I _{OH} = -18 mA	3.0	2.4			
		I _{OH} = -24 mA	3.0	2.2			
/ _{OL}	LOW Level Output Voltage	$I_{OL} = 100 \mu A$	2.3 – 3.6		0.2		
		I _{OL} = 8mA	2.3		0.6		
		I _{OL} = 12 mA	2.7		0.4	V	
		I _{OL} = 16 mA	3.0		0.4		
		I _{OL} = 24 mA	3.0		0.55		
I	Input Leakage Current	$0 \le V_1 \le 5.5V$	2.3 – 3.6		±5.0	μΑ	
OFF	Power-Off Leakage Current	V_I or $V_O = 5.5V$	0		10	μΑ	
CC	Quiescent Supply Current	$V_I = V_{CC}$ or GND	2.3 – 3.6		10		
		$3.6V \le V_1, V_0 \le 5.5V \text{ (Note 5)}$	2.3 – 3.6		±10	μА	
VI _{CC}	Increase in I _{CC} per Input	$V_{IH} = V_{CC} = 0.6V$	2.3 – 3.6		500	μΑ	

DC Electrical Characteristics (Continued) Note 5: Outputs disabled or 3-STATE only.

AC Electrical Characteristics

		$T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, R_L = 500\Omega$							
	B	V _{CC} = 3.3	3V ± 0.3V	V _{CC} =	= 2.7V	$V_{CC}=2.$	5V ± 0.2V	Units	
Symbol	Parameter	C _L = 50 pF		C _L = 50 pF		C _L = 30 pF		Units	
		Min	Max	Min	Max	Min	Max		
t _{PHL}	Propagation Delay	1.5	6.5	1.5	7.5	1.5	7.8	no	
t _{PLH}		1.5	6.5	1.5	7.5	1.5	7.8	ns	
t _{PZL}	Output Enable Time	1.5	8.5	1.5	9.5	1.5	10.5	ns	
t _{PZH}		1.5	8.5	1.5	9.5	1.5	10.5	115	
t _{PLZ}	Output Disable Time	1.5	7.5	1.5	8.5	1.5	9.0	ns	
t _{PHZ}		1.5	7.5	1.5	8.5	1.5	9.0	115	
toshl	Output to Output Skew (Note 6)		1.0					ns	
t _{OSLH}			1.0					115	

Note 6: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

Symbol	Parameter	Conditions	v _{cc}	$T_A = 25^{\circ}C$	Units
Oyillboi	rarameter	Talameter	(V)	Typical	J.III.
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	0.8	W
		$C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$	2.5	0.6	V
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	-0.8	V
		$C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$	2.5	-0.6	٧

Capacitance

Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	V _{CC} = Open, V _I = 0V or V _{CC}	7	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	$V_{CC} = 3.3V$, $V_{I} = 0V$ or V_{CC} , $f = 10$ MHz	25	pF

AC Loading and Waveforms Generic for LCX Family

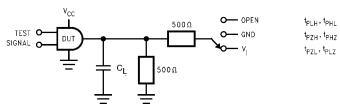
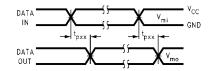
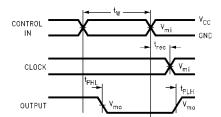


FIGURE 1. AC Test Circuit (C_L includes probe and jig capacitance)

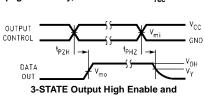
Test	Switch
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6V at $V_{CC} = 3.3 \pm 0.3V$ V_{CC} x 2 at $V_{CC} = 2.5 \pm 0.2V$
t _{PZH} ,t _{PHZ}	GND



Waveform for Inverting and Non-Inverting Functions



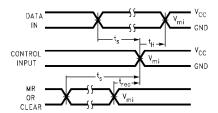
Propagation Delay, Pulse Width and t_{rec} Waveforms



Disable Times for Logic

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3-STATE Output Low Enable and Disable Times for Logic



Setup Time, Hold Time and Recovery Time for Logic

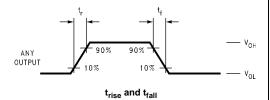
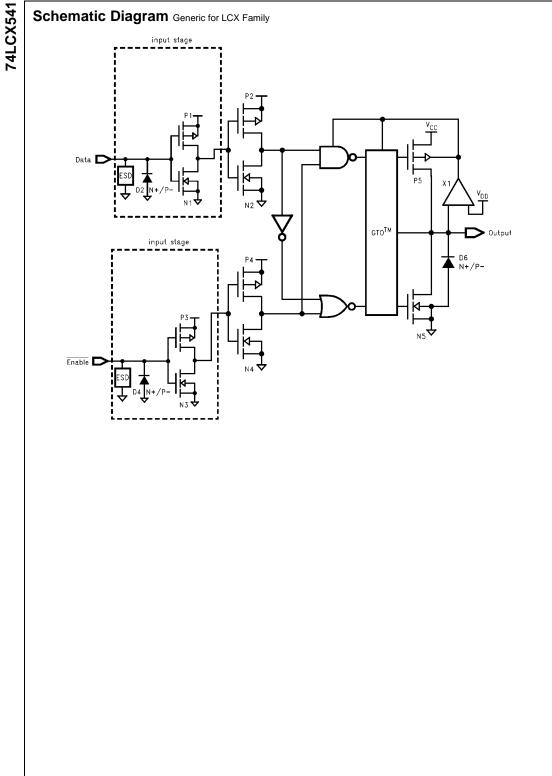
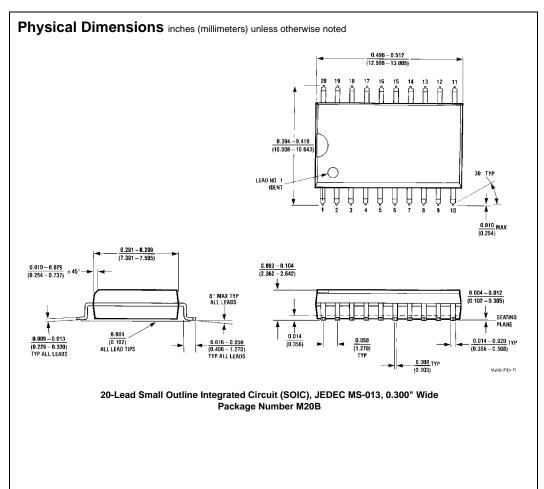
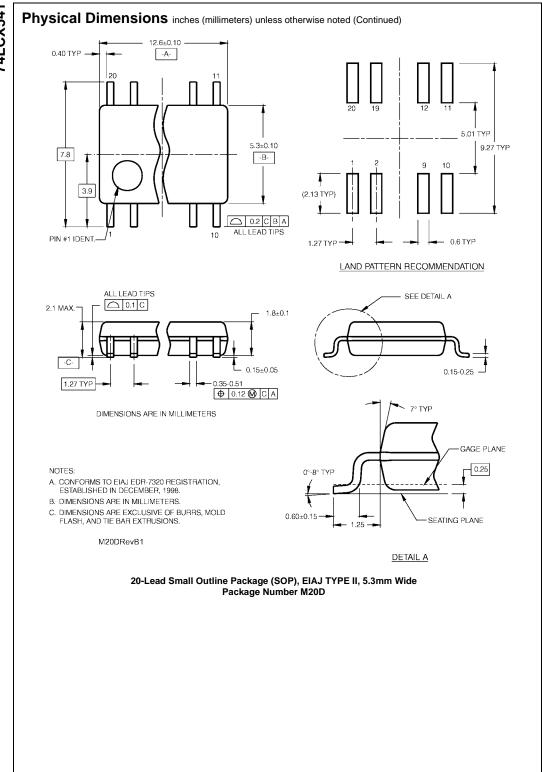


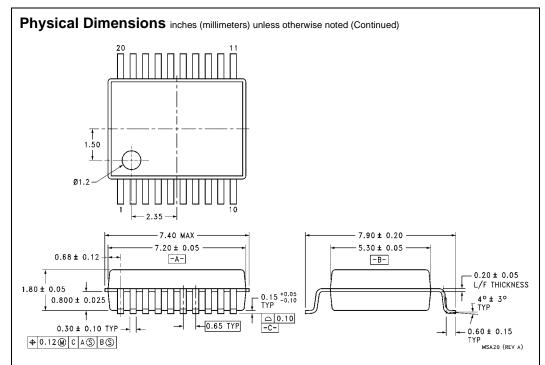
FIGURE 2. Waveforms (Input Pulse Characteristics; $f = 1 \text{MHz}, t_r = t_f = 3 \text{ns}$)

Symbol	V _{cc}				
- Cymbol	3.3V ± 0.3V	2.7V	2.5V ± 0.2V		
V _{mi}	1.5V	1.5V	V _{CC} /2		
V _{mo}	1.5V	1.5V	V _{CC} /2		
V _x	V _{OL} + 0.3V	V _{OL} + 0.3V	V _{OL} + 0.15V		
V _y	V _{OH} – 0.3V	V _{OH} – 0.3V	V _{OH} – 0.15V		









20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide Package Number MSA20

Physical Dimensions inches (millimeters) unless otherwise noted (Continued) -A-4.16 7.72 4.4±0.1 -B-6.4 3.2 0.2 C B A ALL LEAD TIPS PIN #1 IDENT LAND PATTERN RECOMMENDATION □ 0.1 C SEE DETAIL A 0.90+0.15 0.09-0.20 -C-0.1±0.05 0.65 12.00° 0.10 M A B C DIMENSIONS ARE IN MILLIMETERS R0.09 MIN GAGE PLANE NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93. B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. SEATING PLANE 0.6 ± 0.1 R0.09 MIN D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. 1.00 MTC20RevD1 DETAIL A 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Package Number MTC20

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